U.S. Pat. Appl. No. 10/564,969 Amendment After Final dated March 19, 2010 Response to Office action mailed October 28, 2009

Amendments to the Claims

The following Listing of Claims replaces all prior versions, and listings, of claims in the present application.

Listing of Claims:

1-10. (Canceled).

(Currently amended) A method of forming a nozzle plate for droplet deposition apparatus, the nozzle plate defining a nozzle plate plane and comprising a plate having at least one nozzle plate layer and a plurality of nozzles, each nozzle extending through polymeric material located within [[an]] a respective aperture within the nozzle plate, the method being characterised by including the steps of defining a plurality of distinct bodies of polymeric material distributed over the nozzle plate plane, each said body having a periphery, and subsequently forming at least one metal nozzle plate layer by electroforming around said peripheries of said bodies of polymeric material so as to define at least in part the shapes of said apertures.

12-17 (Canceled).

18(Currently amended). A method of forming a nozzle plate component for a droplet deposition apparatus, said method comprising the steps of:

forming a layer of first photoresist material on a substrate;

<u>subsequently</u> selectively exposing and removing <u>first</u> photoresist material to define on the substrate an array of distinct bodies of said first <u>photoresist</u> material;

subsequent to said step of selectively exposing and removing first photoresist material, forming a first plate of metal around said bodies, so as to form a metal nozzle plate having apertures, each aperture containing a body one of said bodies of said first photoresist material; and

U.S. Pat. Appl. No. 10/564,969 Amendment After Final dated March 19, 2010 Response to Office action mailed October 28, 2009

then forming a nozzle extending through each body of said first photoresist material.

19 (Original). A method according to Claim 18, further comprising the step of depositing a metallic layer on the substrate prior to forming of the layer of first photoresist material, said first plate of metal being electroformed with said metallic layer serving as a seed layer.

20-21 (Canceled).

22 (New). A method according to claim 11, wherein said nozzles are formed by ablating through said bodies.

24 (New). A method according to claim 18, wherein said nozzles are formed by ablating through said bodies.